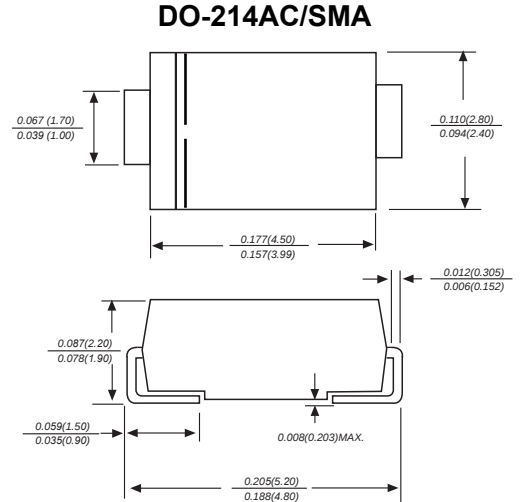


Features

1. The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
2. For surface mounted applications
3. Metal silicon junction, majority carrier conduction
4. Low power loss, high efficiency
5. Built-in strain relief, ideal for automated placement
6. High forward surge current capability
7. High temperature soldering guaranteed:
250 °C/10 seconds at terminals

Mechanical Data

Case : JEDEC DO-214AC/SMA molded plastic body
Terminals : Solderable per MIL-STD-750, Method 2026
Polarity : Color band denotes cathode end
Mounting Position : Any
Weight : 0.003 ounce, 0.093 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS22	SS23	SS24	SS25	SS26	SS28	SS210	SS2150	SS2200	UNITS
Marking Code		SS22	SS23	SS24	SS25	SS26	SS28	SS210	SS2150	SS2200	
Maximum repetitive peak reverse voltage	V _{RMM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL(see fig.1)	I _{AV}	2.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	50									A
Maximum instantaneous forward voltage at 2.0A	V _F	0.55			0.70		0.85			0.95	V
Maximum DC reverse current T _A =25℃ at rated DCblocking voltage T _A =125℃	I _R	0.5							0.2		mA
		10.0				5.0		2.0			
Typical junction capacitance (NOTE 1)	C _J	220			180						pF
Typical thermal resistance (NOTE 2)	R _{θJA}	75.0									℃/W
Operating junction temperature range	T _J	-50 to +125					-50 to +150				℃
Storage temperature range	T _{STG}	-50 to +150									℃

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Typical Characteristics

Fig.1 Forward Current Derating Curve

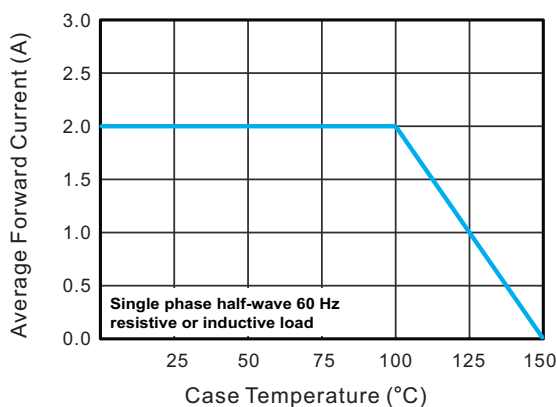


Fig.2 Typical Reverse Characteristics

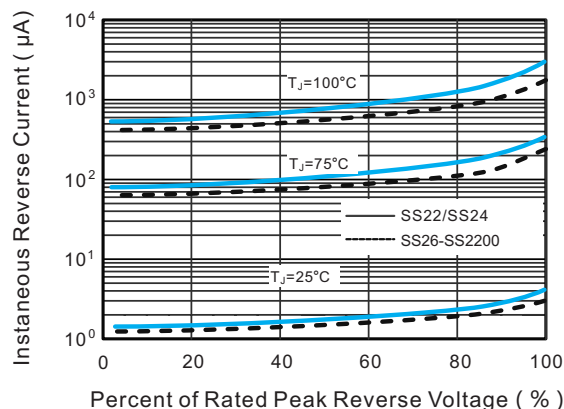


Fig.3 Typical Forward Characteristic

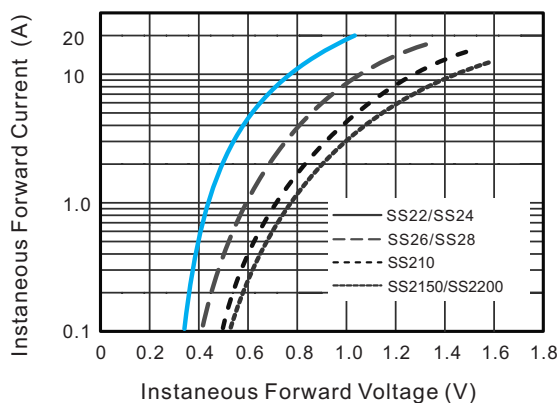


Fig.4 Typical Junction Capacitance

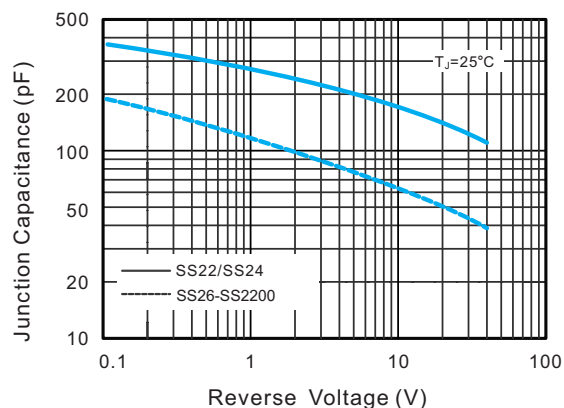


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

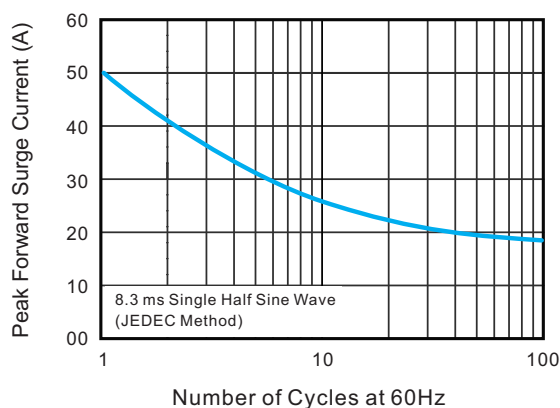
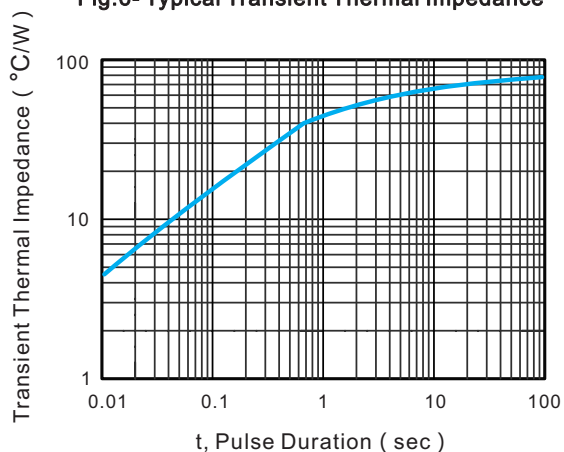
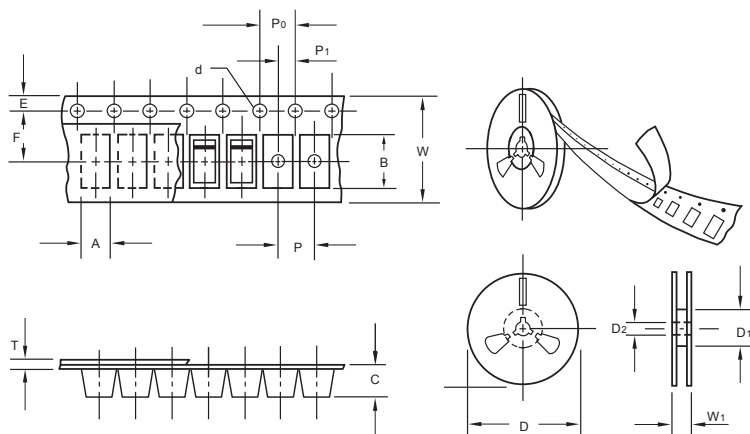


Fig.6 Typical Transient Thermal Impedance



Packing information



unit:mm

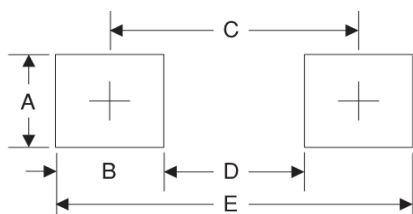
Item	Symbol	Tolerance	SMA
Carrier width	A	0.1	2.80
Carrier length	B	0.1	5.33
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA	7"	2,000	4.0	4,000	183*155*183	178	382*356*392	80,000	16.0
SMA	11"	5,000	4.0	10,000	290*290*38	330	310*310*360	80,000	11.0
SMA	13"	7,500	4.0	15,000	335*335*38	330	350*330*360	120,000	14.5

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.41	0.095
E	5.45	0.215